

Global Epoxy Resin Encapsulation Glue for IC Packaging Supply, Demand and Key Producers, 2026-2032

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Abstracts

The global Epoxy Resin Encapsulation Glue for IC Packaging market size is expected to reach \$ 1949 million by 2032, rising at a market growth of 16.8% CAGR during the forecast period (2026-2032).

Epoxy resin encapsulation glue for IC packaging is a thermosetting polymer material specially designed for integrated circuit (IC) chip protection and packaging. It is based on epoxy resin and modified by adding curing agent, inorganic filler, flame retardant and stress regulator. After curing, it forms a high-strength insulating shell with excellent heat resistance, low dielectric constant, low thermal expansion coefficient and moisture penetration resistance. It can effectively protect the chip from mechanical stress, chemical corrosion and electromagnetic interference. At the same time, it can achieve high thermal conductivity or electromagnetic shielding function by adjusting the formula.

This report studies the global Epoxy Resin Encapsulation Glue for IC Packaging production, demand, key manufacturers, and key regions.

This report is a detailed and comprehensive analysis of the world market for Epoxy Resin Encapsulation Glue for IC Packaging and provides market size (US\$ million) and Year-over-Year (YoY) Growth, considering 2025 as the base year. This report explores demand trends and competition, as well as details the characteristics of Epoxy Resin Encapsulation Glue for IC Packaging that contribute to its increasing demand across many markets.

Highlights and key features of the study

Global Epoxy Resin Encapsulation Glue for IC Packaging total production and demand,

2021-2032, (Kilotons)

Global Epoxy Resin Encapsulation Glue for IC Packaging total production value, 2021-2032, (USD Million)

Global Epoxy Resin Encapsulation Glue for IC Packaging production by region & country, production, value, CAGR, 2021-2032, (USD Million) & (Kilotons), (based on production site)

Global Epoxy Resin Encapsulation Glue for IC Packaging consumption by region & country, CAGR, 2021-2032 & (Kilotons)

U.S. VS China: Epoxy Resin Encapsulation Glue for IC Packaging domestic production, consumption, key domestic manufacturers and share

Global Epoxy Resin Encapsulation Glue for IC Packaging production by manufacturer, production, price, value and market share 2021-2026, (USD Million) & (Kilotons)

Global Epoxy Resin Encapsulation Glue for IC Packaging production by Type, production, value, CAGR, 2021-2032, (USD Million) & (Kilotons)

Global Epoxy Resin Encapsulation Glue for IC Packaging production by Application, production, value, CAGR, 2021-2032, (USD Million) & (Kilotons)

This report profiles key players in the global Epoxy Resin Encapsulation Glue for IC Packaging market based on the following parameters - company overview, production, value, price, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include 3M, Henkel, Parker LORD, SolEpoxy, Epic Resins, Robnor ResinLab, Guangdong Anders Industrial Co., Ltd., Shantou Niche-Tech Kaiser Co., Ltd., Dongguan Huachuang Electronic Materials Co., Ltd., Guangdong Wanmu New Material Technology Co., Ltd., etc.

This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals.

Stakeholders would have ease in decision-making through various strategy matrices used in analyzing the World Epoxy Resin Encapsulation Glue for IC Packaging market

Detailed Segmentation:

Each section contains quantitative market data including market by value (US\$ Millions), volume (production, consumption) & (Kilotons) and average price (US\$/Ton) by manufacturer, by Type, and by Application. Data is given for the years 2021-2032 by year with 2025 as the base year, 2026 as the estimate year, and 2027-2032 as the forecast year.

Global Epoxy Resin Encapsulation Glue for IC Packaging Market, By Region:

United States

China

Europe

Japan

South Korea

ASEAN

India

Rest of World

Global Epoxy Resin Encapsulation Glue for IC Packaging Market, Segmentation by Type:

One-component

Two-component

Global Epoxy Resin Encapsulation Glue for IC Packaging Market, Segmentation by Application:

Consumer Electronics

Computers and Data Centers

Automotive Electronics

Medical Electronics

Industrial

Others

Companies Profiled:

3M

Henkel

Parker LORD

SolEpoxy

Epic Resins

Robnor ResinLab

Guangdong Anders Industrial Co., Ltd.

Shantou Niche-Tech Kaiser Co., Ltd.

Dongguan Huachuang Electronic Materials Co., Ltd.

Guangdong Wanmu New Material Technology Co., Ltd.

Beijing Kmt Technology Co., Ltd

Yongdeji Technology (Suzhou) Co., Ltd.

Shanghai Dodi Polymer Material Co., Ltd.

Hubei Huitian New Materials Co., Ltd.

Dongguan Sains Industrial Co., Ltd.

Key Questions Answered:

1. How big is the global Epoxy Resin Encapsulation Glue for IC Packaging market?

2. What is the demand of the global Epoxy Resin Encapsulation Glue for IC Packaging market?
3. What is the year over year growth of the global Epoxy Resin Encapsulation Glue for IC Packaging market?
4. What is the production and production value of the global Epoxy Resin Encapsulation Glue for IC Packaging market?
5. Who are the key producers in the global Epoxy Resin Encapsulation Glue for IC Packaging market?
6. What are the growth factors driving the market demand?

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